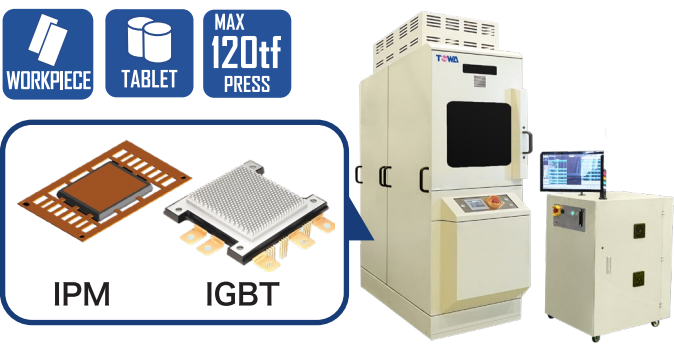


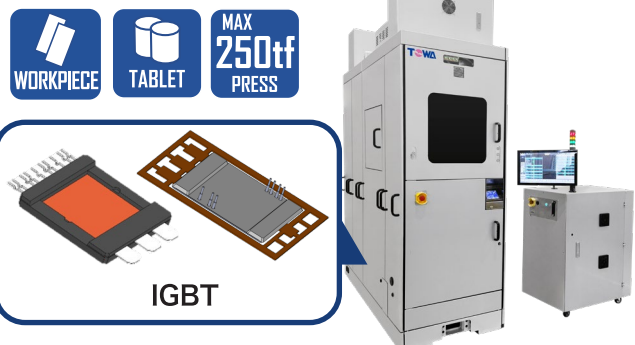
YPM1120

Transfer molding system
for automotive and power packages



YPD1250

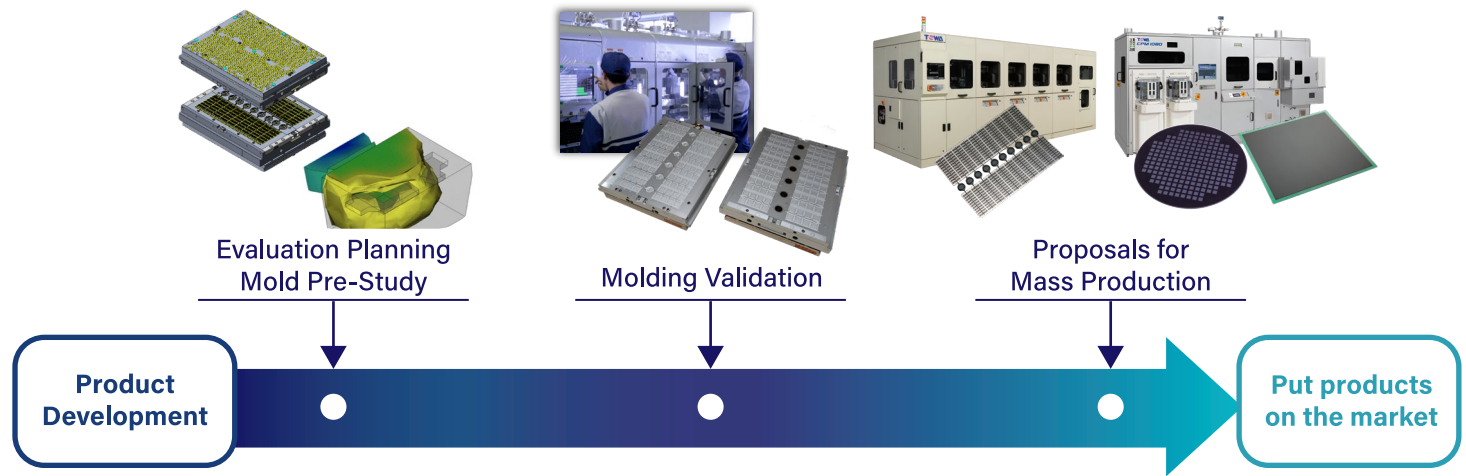
Transfer molding system
for large power packages



Items		Unit	Description	Description
Model		—	YPM1120	YPD1250
Machine type		—	Manual	Manual
Workpiece type		—	Substrate・Lead frame	Substrate・Lead frame
Workpiece size	Length	mm	150—290	70—300
	Width	mm	35—100	35—130
	Thickness	mm	—	25.0 (Max.)
Molding compound	Diameter	mm	φ 13, 14, 16, 18, 20	φ 13, 14, 16, 18, 20
	Length	mm	14.3—35.0	1pcs: 14.3—35.0 / 2pcs: 70.0 (Max.)
External dimensions	Width	mm	735 (Press) / 625 (Control unit)	900 (Press) / 920 (Control unit)
	Depth	mm	1,765	2,235
	Height	mm	2,450	2,808
Weight		ton	4	7
Number of workpieces per cycle		workpiece	2	8 (Max.)
Clamp capacity		kN / (tf)	196.0—1,177.0 / 20.0—120.0	490.0—2,469.0 / 50.0—250.0
Transfer capacity		kN / (tf)	3.92—49.0 / 0.4—5.0	3.92—117.6 / 0.40—12.0
Moving pin		—	Upper / Lower	Upper / Lower
Release film width	Upper chase	mm	100—300	100—400
	Lower chase	mm	—	37—130

・The figures shown are based on standard machine specifications.
・The above specification are subject to change without prior notice.
・For special requirements, please consult your local TOWA representative.

Laboratory Initiatives



Global Network



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Website



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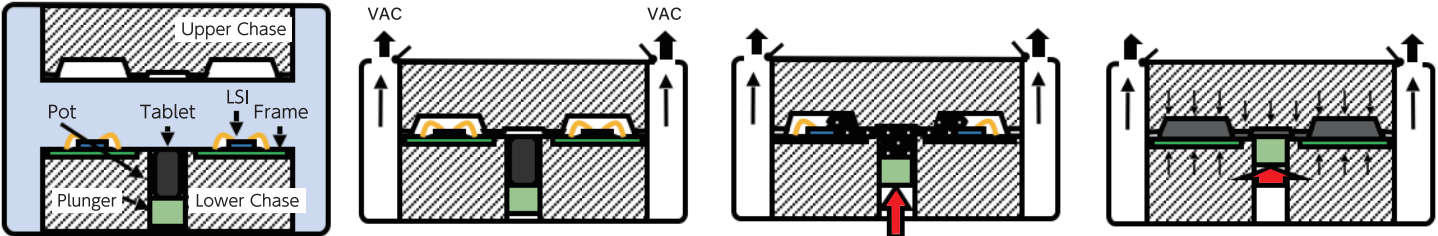
Creating value through innovation



Transfer Molding

Injection Mold

Transfer molding is the molding method of filling the cavity with resin melted in the pot and then curing it.

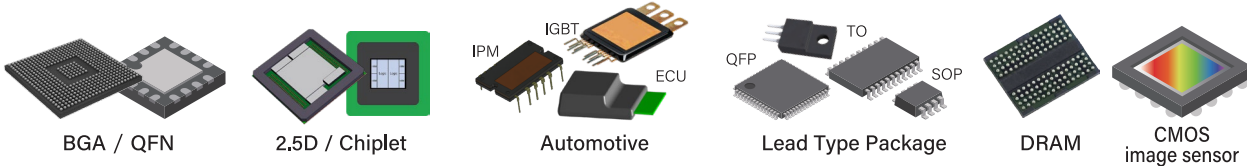


Frame & Tablet set Frame clamp & High vacuum condition Injection Hold Pressure and Cure

Feature

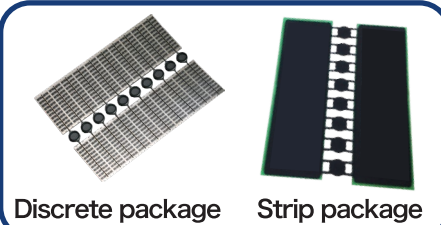
- Applicable for complex shaped package
Applicable for various shaped packages including individual package and double side package.
- Suitable for exposure molding including chip and substrate exposure package.

Target product



YPM1180

All-in-one transfer molding system for high quality molding



Items		Unit	Description
Model		—	YPM1180
Machine type		—	Manual
Workpiece type		—	Substrate・Lead frame
Workpiece size	Length	mm	150—300
	Width	mm	35—100
Molding compound	Diameter	mm	φ 13, 14, 16, 18, 20
	Length	mm	14.3—35.0
External dimensions	Width	mm	1,381.5
	Depth	mm	1,550
	Height	mm	1,980
Weight		ton	4.2
Number of workpieces per cycle		workpiece	2
Clamp capacity		kN／(tf)	294.0—1,764.0／30.0—180.0
Transfer capacity		kN／(tf)	3.92—49.0／0.4—5.0
Release film width		mm	100—300

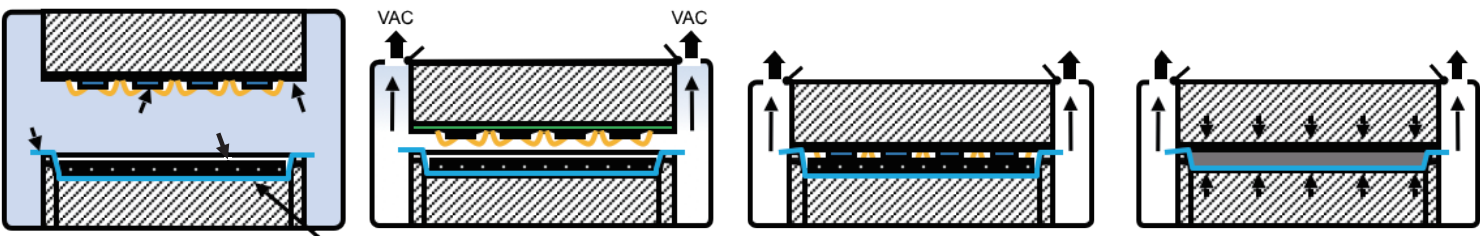
Compression Molding

Compression Mold

Compression molding is the molding method that compresses and cures granular or liquid resin within the cavity with less resin flow.

※ **Cavity Down Structure is introduced.**

Dispense resin on the bottom cavity and immerse the workpiece set in the upper mold into the melted resin

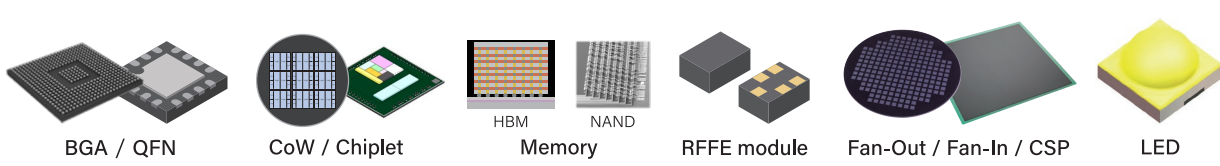


Frame and Film + Resin set High vacuum condition Frame clamp & compression Hold Pressure and Cure

Feature

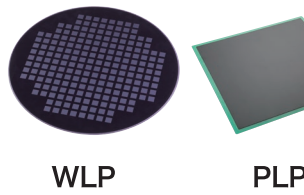
- Less resin flow
Less resin flow prevents defects including chip shift and wire sweep.
- Suitable for wafer / panel molding
Uniform resin dispense to the end face of workpiece enables high quality molding.

Target product



CPM1080

Compression molding system for high-quality and low-cost WLP/PLP molding processes



Items		Unit	Description
Model		—	CPM1080
Machine type		—	Manual Semi-Auto
Workpiece type		—	Panel・Wafer
Workpiece size	Panel	mm	□320 (Max.)
	Wafer	mm	φ 320 (Max.)
Molding compound		—	Granular・Liquid
External dimensions	Width	mm	1,388 2,950
	Depth	mm	1,650 2,010
	Height	mm	1,980 1,980
Weight		ton	4.4 6.3
Number of workpieces per cycle		workpiece	1 1
Clamp capacity		kN／(tf)	98.0—784.0／10.0—80.0
Clamp speed		mm／sec	100 (Max.)
Release film width		mm	440 (Max.)

CPM1180

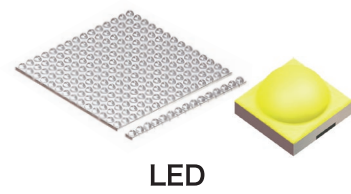
Compression molding system for large size PLP molding to meet industry needs



Items		Unit	Description
Model		—	CPM1180
Machine type		—	Manual Semi-Auto
Workpiece type		—	Panel・Wafer
Workpiece size	Panel	mm	625 × 620
	Wafer	mm	φ 450 (Max.) —
Molding compound		—	Granular
External dimensions	Width	mm	2,000 4,395
	Depth	mm	2,670 2,670
	Height	mm	2,285 2,285
Weight		ton	12.3 22.4
Number of workpieces per cycle		workpiece	1 1
Clamp capacity		kN／(tf)	49.0—1,764.0／5.0—180.0
Clamp speed		mm／sec	70 (Max.)
Release film width		mm	740 (Max.)

LCM1010

Automatic compression molding system for mass production of LED packages



Items		Unit	Description
Model		—	LCM1010
Machine type		—	Manual Semi-Auto
Workpiece type		—	Substrate・Lead frame・Wafer
Workpiece size	mm	1 strip type: 6 inch wafer／70—150(W)×50—150(L) 2 strip type: 45—70(W)×50—150(L)	1 strip type: 6 inch wafer／70—150(W)×70—150(L) 2 strip type: 45—70(W)×50—150(L)
Molding compound		—	Liquid
External dimensions	Width	mm	1,147 1,500—3,420
	Depth	mm	1,400 1,400
	Height	mm	1,700 1,700
Weight		ton	2.1 2.6—8.0
Number of workpieces per cycle		workpiece	Strip: 1 or 2／Wafer: 1
Clamp capacity		kN／(tf)	29.4—98.0／3.0—10.0
Clamp speed		mm／sec	50 (Max.) 52 (Max.)
Release film width		mm	1 strip: 210 (Max.)／2 strip: 110 (Max.)

•The figures shown are based on standard machine specifications.
•The above specification are subject to change without prior notice.
•For special requirements, please consult your local TOWA representative.
•The external dimensions of CPM1080 are for the granular resin specification.